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N. Thompson
8-28-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/148,723
Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner D. Tugbang
Attorney's Docket No. MI22-981
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

RESPONSE TO JUNE 18, 2002 EX PARTE QUAYLE OFFICE ACTION

To: Box Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

From: Frederick M. Fliegel, Ph.D.
(Tel. 509-624-4276; Fax 509-838-3424)
Wells St. John P.S.
601 West First Avenue, Suite 1300
Spokane, WA 99201-3828

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Responsive to the Ex Parte Quayle Office Action dated June 18, 2002,
Applicant amends and remarks as follows:

AMENDMENTS